

## REMARKS

In the 3/12/02 Office Action there were 16 claims that were rejected in overlapping rejections under 35USC 112, 102 103 involving eight references.

For perspective, the invention provides a very efficient electronic apparatus cooling principle wherein, a planar, radiation to liquid, heat transfer component is positioned in contact with the surface of the structure that transfers the heat and further to a gaseous cooling system.

Examiner's suggestions concerning the absence of structural limitations and antecedent points are much appreciated.

In essence, considering a chip as a radiating surface example, what is presented here in the claims are interdependent limitations directed to the combination of a planar radiation to liquid heat transfer component at the chip surface followed by the liquid to gas heat exchanger.

In view of the rewriting of the claims only general comments with respect to the art are being advanced. It is submitted that nowhere in the art has the planar radiation to liquid heat conversion at the chip surface appeared. It is further submitted that a system has not appeared wherein there is radiation to liquid heat conversion at the chip surface followed by transfer to a gaseous medium elsewhere in the apparatus.

Considering first the 35USC112 points.

The response to the antecedent support the problem is considered resolved in the new claim 17.

The point concerning claim 6 is considered resolved in the cancellation of claim 6.

Considering the rejections on art. While no element by element reference to claim limitation between the references and the invention has been advanced applicants find nowhere in the art a planar radiation to liquid heat conversion at the chip surface and no radiation to liquid heat conversion at the chip surface followed by transfer to a gaseous medium elsewhere in the apparatus in either a single reference or in any logical combination of references.

The application is considered to be in condition for allowance.

It is respectfully urged that a temperature control structure involving the interdependent criteria in applicants claims has not appeared heretofore in the art and that applicants' contribution constitutes a major step in the art.

Respectfully submitted,

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